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| Objective |
| Batch name: Process template |
| This process flows is a guideline on how to spin coat, develop and rinse AZ MiR 701 on substrates as Si, SiO2 and Borofloat, using the Spin Track 1 + 2. |

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| Step Heading | Equipment | **AZ MiR 701 spinning on Si, SiO2, Borofloat** | Comments |
| 1. Pretreatment and spin coat of AZ MiR 701 | | |  |
| * 1. Pretreatment | BHF dip  *or*  Spin Track 1 + 2 | BHF dip for Si substrates (30 sec, H2O 5 min)  Inline HMDS for SiO2 and Borofloat |  |
| * 1. Coat wafers | Spin Track 1 + 2 | **Resist:** AZ MiR 701  **Softbake:** 1 min @ 90 °C  **Spin Track Flows:**  T1 MiR 701 2um no HMDS  T1 MiR 701 2um with HMDS |  |
| 1. UV Exposure | | |  |
| * 1. Exposure | KS Aligner | Hard contact  **Exposure time:** 25 sec @ 7mW/cm2 |  |
| 1. Post Exposure Bake | | |  |
| * 1. Post Exposure Bake | Spin Track 1 + 2 | **Post Exposure Bake:** 1 min @ 110 °C  **Recipe:** T2 MiR 701 PEB | 1 mm proximity |
| 1. Development, Rinse, and Dry | | |  |
| * 1. Development, rinse and dry | Developer TMAH UV-lithography | Develop in TMAH for 60sec puddle |  |
| 1. Inspection | | |  |
| * 1. Inspection | Optical microscope |  |  |